

Final Product Change Notification

202111011F01: LPC804M101JHI33 addition of 2nd source wafer fab

Note: This notice is NXP Company Proprietary.

Issue Date: Nov 22, 2021 Effective date: Feb 20, 2022

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Management summary

Powerchip (PSMC) will be added as a second source wafer fab for the LPC804M101JHI33.

Change Category

Fab Process	[]Assembly Process	[]Product Marking	[]Test Process	[]Design
[]Wafer Fab Materials	[]Assembly Materials	[]Mechanical Specification	[]Test Equipment	[]Errata
[X]Wafer Fab Location	[]Assembly Location	[]Packing/Shipping/Labeling	[]Test Location	[]Electrica spec./Test coverage
[]Firmware	[]Other			

PCN Overview

Description

Powerchip will be added as a second source wafer fab for the LPC804M101JHI33.

- No change in data sheet
- No change in ordering part number / 12NC
- No change in assembly materials
- Assembly and final test location remains unchanged at NXP Assembly and Test Kaohsiung (ATKH)

Reason

To ensure wafer supply with increased capacity.

Identification of Affected Products

Top Side Marking

The first character of the last line of the top side device marking contains the wafer fab code. "S"=PSMC, "Z"=SSMC.

Product Availability

Sample Information

Samples are available from Dec 05, 2021

Production

Planned first shipment Feb 10, 2022

Anticipated Impact on Form, Fit, Function, Reliability or Quality

Top side marking changes to indicate the wafer fab.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Dec 22, 2021.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Tim Camenzind

Position Quality Manager

e-mail

address tim.camenzind@nxp.com

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NXP Quality Management Team.

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High Tech Campus, 5656 AG Eindhoven, The Netherlands

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Changed Orderable Part#	12NC	Product Type	Product Description	Package Outline	Package Description	Product Status	Customer Specific Indicator	Product Line
LPC804M101JHI33Y	935346816518	3 LPC804M101JHI33	32-bit ARM Cortex-M0+	H(V)QFN32	SOT617-11	RFS	No	BLM1
LPC804M101JHI33E	935346816551	LPC804M101JHI33	32-bit ARM Cortex-M0+	H(V)QFN32	SOT617-11	RFS	No	BLM1